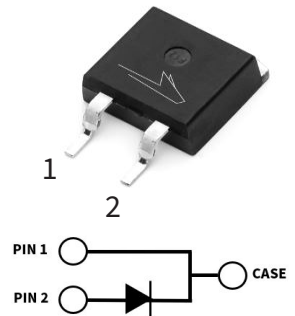


C6D20065G

6th Generation 650 V, 20 A Silicon Carbide Schottky Diode

Description

With the performance advantages of a Silicon Carbide (SiC) Schottky Barrier diode, power electronics systems can expect to meet higher efficiency standards than Si-based solutions, while also reaching higher frequencies and power densities. SiC diodes can be easily paralleled to meet various application demands, without concern of thermal runaway. In combination with the reduced cooling requirements and improved thermal performance of SiC products, SiC diodes are able to provide lower overall system costs in a variety of diverse applications.



Package Types: TO-263-2
Marking: C6D20065G

Features

- Low Forward Voltage (V_F) Drop with Positive Temperature Coefficient
- Zero Reverse Recovery Current / Forward Recovery Voltage
- Temperature-Independent Switching Behavior
- Low Leakage Current (I_R)

Applications

- Industrial Power Supplies
- Uninterruptible & AUX Power Supplies
- Switch Mode Power Supplies
- Solar Inverters
- Power Factor Correction
- Server/Telecom Power Supplies

Maximum Ratings ($T_c = 25^\circ\text{C}$ Unless Otherwise Specified)

Parameter	Symbol	Value	Unit	Test Conditions	Notes
Repetitive Peak Reverse Voltage	V_{RRM}	650	V		
DC Blocking Voltage	V_{DC}	650			
Continuous Forward Current	I_F	64	A	$T_J = 25^\circ\text{C}$	Fig. 3
		32		$T_J = 125^\circ\text{C}$	
		20		$T_J = 150^\circ\text{C}$	
Repetitive Peak Forward Surge Current	I_{FRM}	78	A	$T_c = 25^\circ\text{C}, t_p = 10\text{ ms}, \text{Half Sine Wave}$	
		45		$T_c = 110^\circ\text{C}, t_p = 10\text{ ms}, \text{Half Sine Wave}$	
Non-Repetitive Forward Surge Current	I_{FSM}	135	A	$T_c = 25^\circ\text{C}, t_p = 10\text{ ms}, \text{Half Sine Wave}$	Fig. 8
		111		$T_c = 110^\circ\text{C}, t_p = 10\text{ ms}, \text{Half Sine Wave}$	
Non-Repetitive Peak Forward Surge Current	$I_{F,Max}$	1550	A	$T_c = 25^\circ\text{C}, t_p = 10\text{ }\mu\text{s}, \text{Pulse}$	
		1290		$T_c = 110^\circ\text{C}, t_p = 10\text{ }\mu\text{s}, \text{Pulse}$	
Power Dissipation	P_{tot}	163	W	$T_J = 25^\circ\text{C}$	Fig. 4
		71		$T_J = 110^\circ\text{C}$	
i^2t value	$\int i^2 dt$	91	A^2s	$T_c = 25\text{C}, t_p=10\text{ms}$	
		62		$T_c = 110\text{C}, t_p=10\text{ms}$	

Electrical Characteristics

Parameter	Symbol	Typ.	Max.	Unit	Test Conditions	Notes
Forward Voltage	V_F	1.27	1.50	V	$I_F = 20\text{ A}, T_j = 25\text{ }^\circ\text{C}$	Fig. 1
		1.37	1.60		$I_F = 20\text{ A}, T_j = 175\text{ }^\circ\text{C}$	
Reverse Current	I_R	5	30	μA	$V_R = 650\text{ V}, T_j = 25\text{ }^\circ\text{C}$	Fig. 2
		40	300		$V_R = 650\text{ V}, T_j = 175\text{ }^\circ\text{C}$	
Total Capacitive Charge	Q_C	62		nC	$V_R = 400\text{ V}, T_j = 25\text{ }^\circ\text{C}$	Fig. 5
Total Capacitance	C	1153		pF	$V_R = 0\text{ V}, T_j = 25\text{ }^\circ\text{C}, f = 1\text{ MHz}$	Fig. 6
		120			$V_R = 200\text{ V}, T_j = 25\text{ }^\circ\text{C}, f = 1\text{ MHz}$	
		96			$V_R = 400\text{ V}, T_j = 25\text{ }^\circ\text{C}, f = 1\text{ MHz}$	
Capacitance Stored Energy	E_C	9.5		μJ	$V_R = 400\text{ V}$	Fig. 7

Notes:

SiC Schottky Diodes are majority carrier devices, so there is no reverse recovery charge.

Thermal & Mechanical Characteristics

Parameter	Symbol	Value	Unit	Notes
Thermal Resistance, Junction to Case (Typical)	$R_{\theta, JC(TYP)}$	0.76	$^\circ\text{C} / \text{W}$	
Junction Temperature	T_j	-55 to +175	$^\circ\text{C}$	
Case & Storage Temperature	T_c	-55 to +175		

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Notes
Human Body Model	HBM	Class 3B ($\geq 8000\text{ V}$)
Charge Device Model	CDM	Class C3 ($\geq 1000\text{ V}$)

Typical Performance

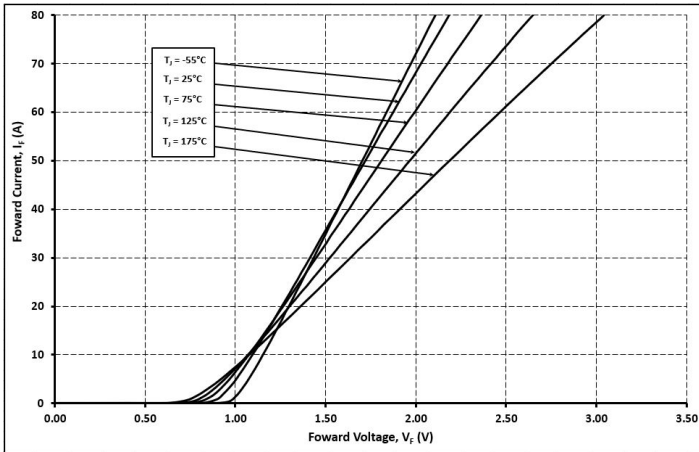


Figure 1
Forward Characteristics

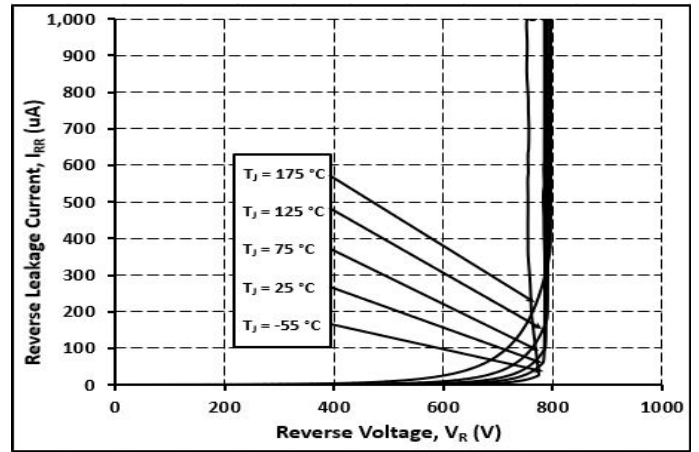


Figure 2
Reverse Characteristics

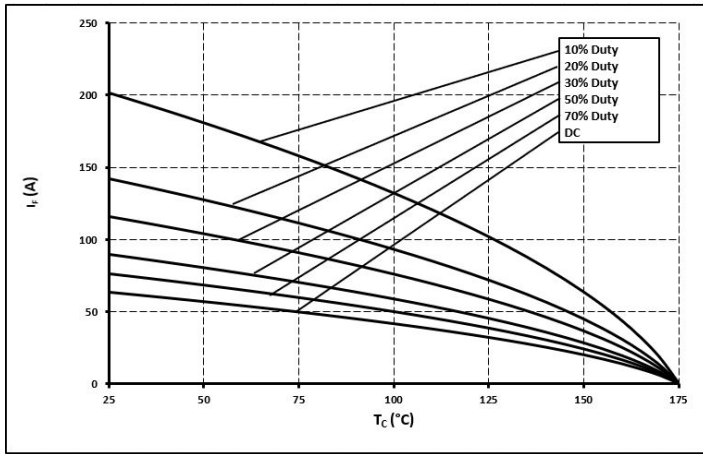


Figure 3
Current Derating

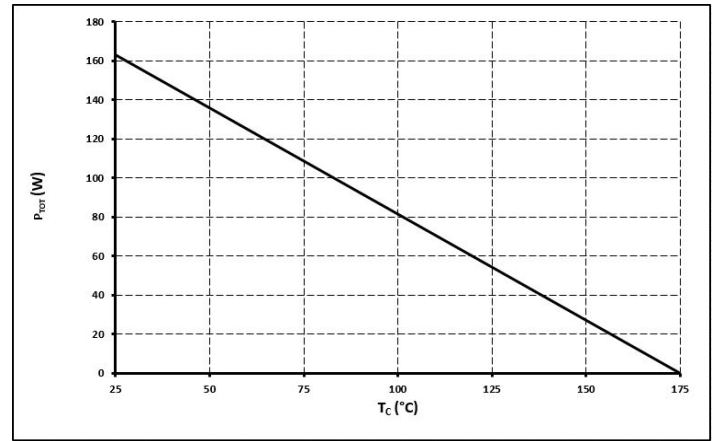


Figure 4
Power Derating

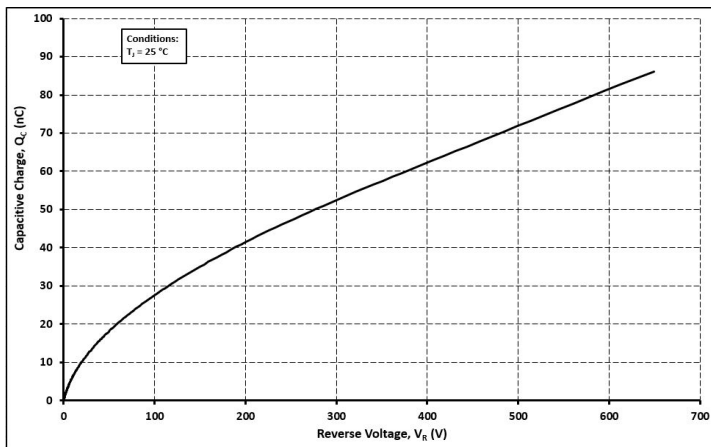


Figure 5
Total Capacitance Charge vs. Reverse Voltage

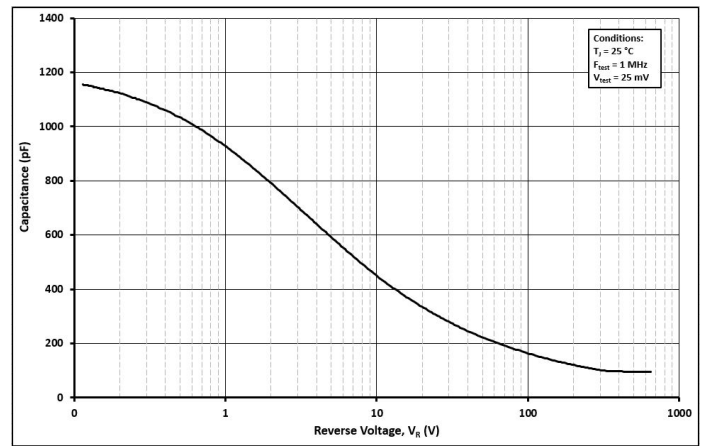


Figure 6
Capacitance vs. Reverse Voltage



Typical Performance

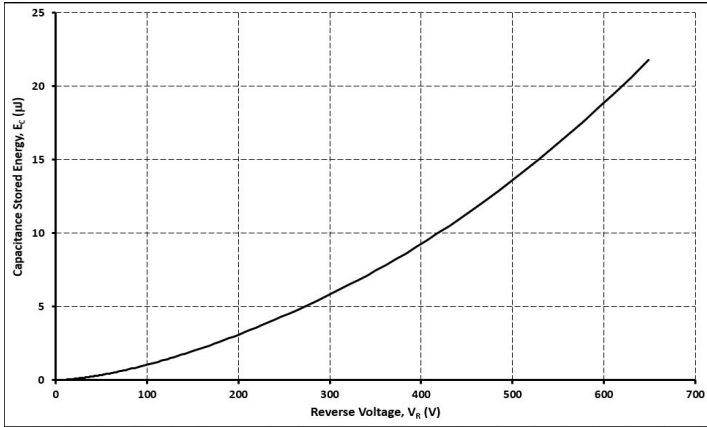


Figure 7
Capacitance Stored Energy

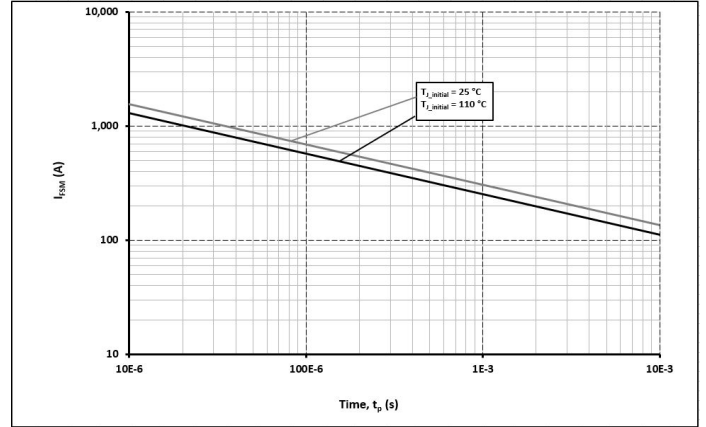


Figure 8
Non-Repetitive Peak Forward Surge Current vs. Pulse Duration

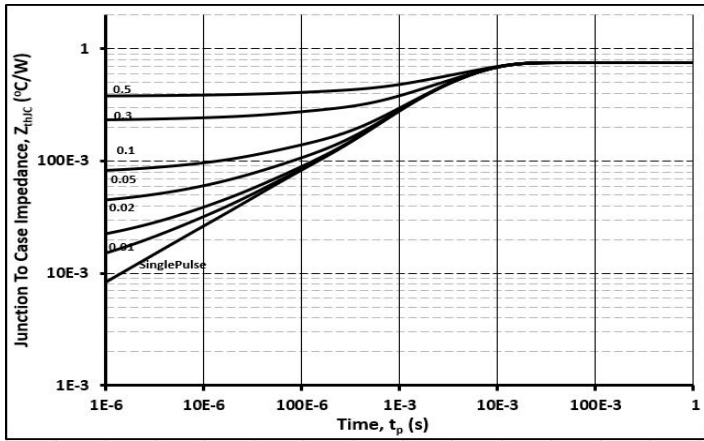
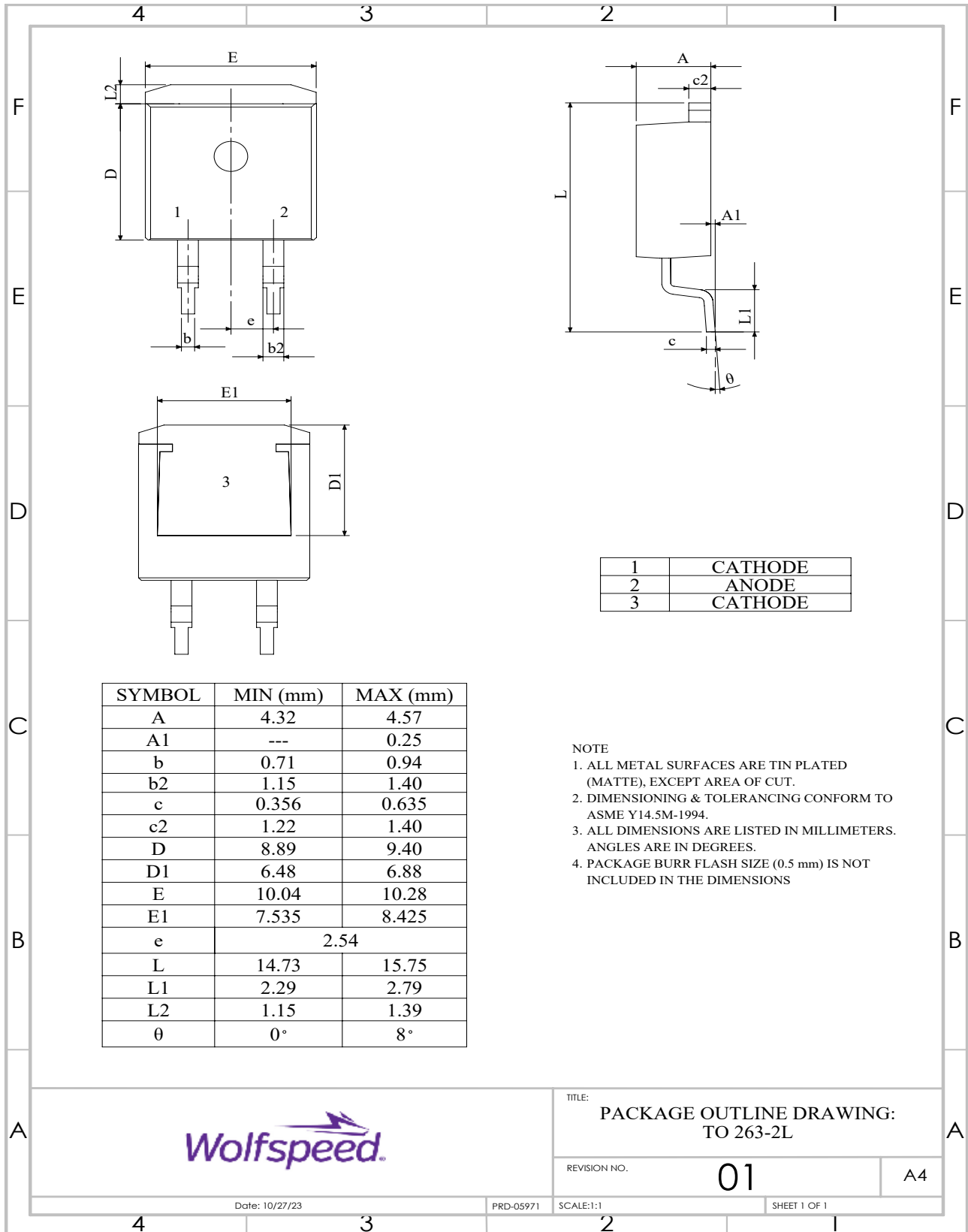


Figure 9
Transient Thermal Impedance

Package Dimensions & Pin-Out

Package: TO-263-2



TITLE:
PACKAGE OUTLINE DRAWING:
TO 263-2L

REVISION NO. **01** A4

Date: 10/27/23

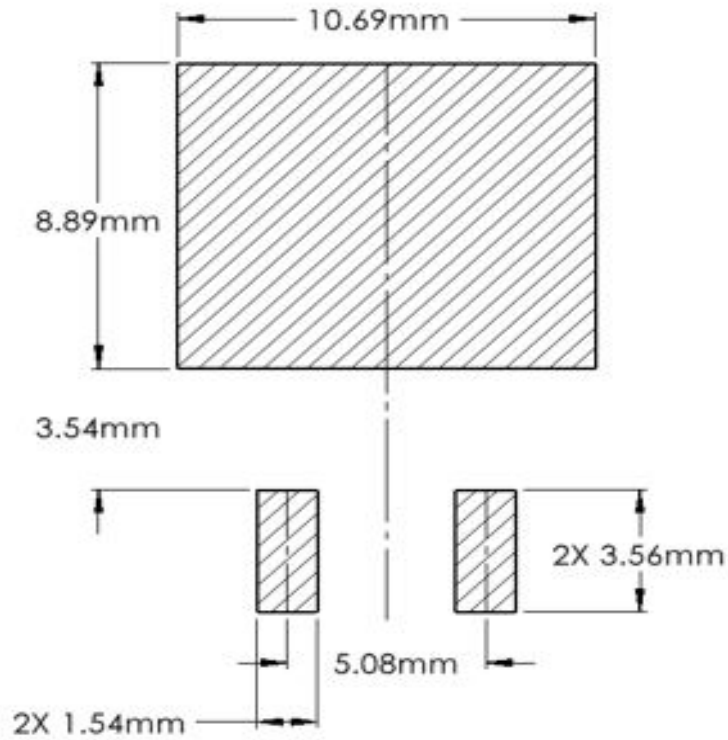
PRD-05971

SCALE:1:1

SHEET 1 OF 1

Recommended Solder Pad Layout

Primary dimensions shown in mm.



Product Ordering Information

Order Number	Packing Type
C6D20065G	Tube
C6D20065G-TR	Tape and Reel

REACH, RoHS, and Halogen-Free compliance documentation available for this product.



Revision History

Document Version	Date of Release	Description of Changes
0	March-2023	Initial Release
1	November-2023	Corrected Package Drawing L and L1

Notes & Disclaimer

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Contact info:

4600 Silicon Drive
Durham, NC 27703 USA
Tel: +1.919.313.5300
www.wolfspeed.com/power